Super power®

金線銲線機

SPB-TS668(HC系列)

GOLD WIRE BALL BONDER

TS668說明：

(1)使用電源:110V/220V ,50/60HZ
(2)適用線徑:1.0mil~1.2mil
(3)顯微鏡放大倍數: 15X .30X 兩段式
(4)銲接溫度:120℃~200℃;最高溫度:400℃
(5)銲接壓力:第一點,第二點可個別調整設定
(6)夾具座移動範圍:10m/m
(7)第二點銲線可設定自動位移,位移距離可設定.
(8)金球尺寸:2mil～4mil之線徑,可自行設定
(9)銲接距離:手動及設定自動兩種位移方式.
(10)採用高壓放電方式燒球.
(11)外型尺寸:600(深)X570(寬)X520(高)mm,重量: 40 KG

1.Power:110/220V,50/60HZ.
2.Suitable wire diameter:1.0mil~1.2mil.
3.Microscope magnification:15X,30X two-stage types
4.Bonding temperature:120℃~200℃.Maximum temperature:400℃
5.Bonding force:first point and second point can be separately set and adjusted.
6.Range of clamping base movement:10m/m.
7.The second point bonding operation can be set to automatically move bonding point & bonding distance can be set.
8.Ball size:2mil to 4mil of wire diameter,and diameter can be adjusted.
9.Bonding distance: manual& setting automatically.
10.This machine is equipped with high voltage discharge for ball burning.
11.Dimensions:600(D)X570(W)X520(H)mm.Weight:40Kg.

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